

## ABSTRACT OF THE DISCLOSURE

A method of fabricating a semiconductor integrated circuit device includes performing a wafer process to a plurality of wafers so as to form a plurality of semiconductor integrated circuit devices over each of the wafers, performing a first electrical test to a first set of wafers selected from the plurality of wafers formed in the wafer process and accommodated in a first wafer cassette placed in a wafer prober, and performing a second electrical test to a second set of wafers selected from the plurality of wafers formed in the wafer process and accommodated in a second wafer cassette placed in the wafer prober by automatically changing a test object to the second set of wafers.